



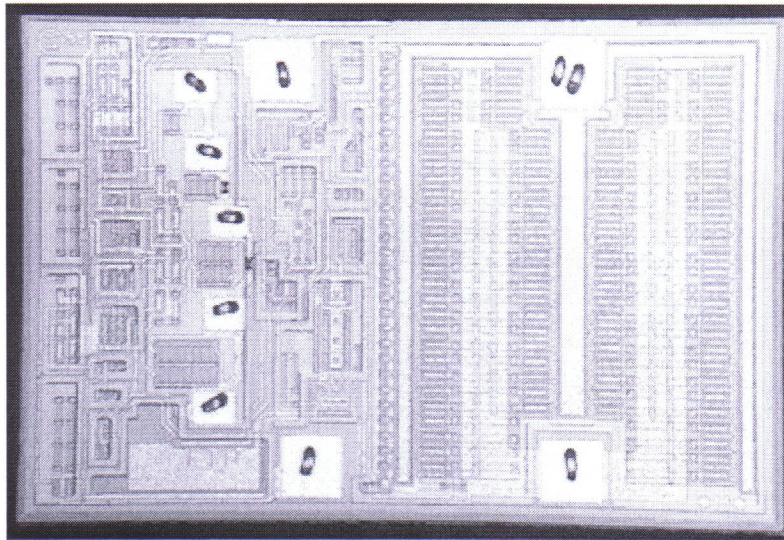
# Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

GND

V INPUT



V OUT (Sensor)

V OUT

Top Material: Al  
Backside Material: TiNiAg  
Bond Pad Size: 0.0055"  
Backside Potential: GND  
Mask Ref: F77T

APPROVED BY:MG

DIE SIZE :0.056" X 0.083"

DATE: 9/23/09

MFG:RCA

THICKNESS: 0.010 +/- 0.002

P/N:MC7805C